

# MATERIAL DECLARATION SHEET



Material #	<b>2QSP28 Series</b>	
Product Line	Integrated Passive & Active Devices	
Date	5/27/2004	
RoHS Compliant?	Yes	

## COMPONENT DETAILS

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	Lead Frame	Lead Frame	0.086800	Cu	7440-50-8	58.220	60.940	
				Sn	7440-31-5	2.7180		
2	Wafer	Silicon	0.014340	Silicon	7440-21-3	9.9680	10.070	
				Other material		0.1007		
3	Gold Bond wire	Conductor	0.000408	Au	7440-57-5	0.2386	0.2865	
				SI		0.0029		
4	Silver paste	Die Attach	0.000808	Ag	7440-22-4	0.4425	0.5673	
				Epoxy		0.1248		
5	Molding Component	Outer	0.040100	Silica fused	60676-86-0	23.930	28.150	
				Epoxy resin	68928-70-1	2.8150		
				Phenol resin	29690-82-2	1.4080		
		Total weight	0.142426					

Lead Part Number Example: 2QSP28-RJ2-272  
 Pb Free Part Number Example: 2QSP28-RJ2-272LF

Note: Avg. mass and sum data is a % of the component weight.  
 It is the responsibility of the user to ensure that the latest revision is being accessed on the website.